



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



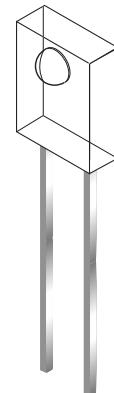
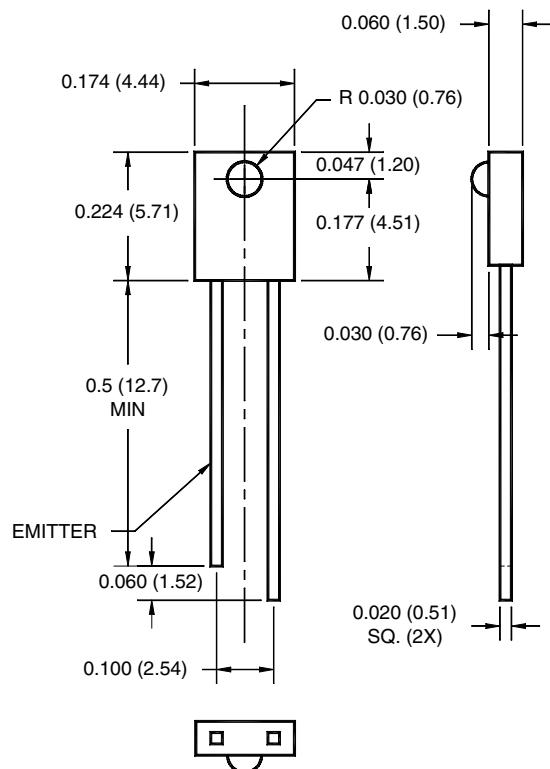
## Contact us

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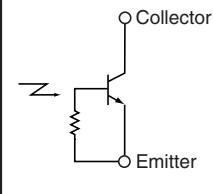
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**PACKAGE DIMENSIONS**



**SCHEMATIC**



**NOTES:**

1. Dimensions for all drawings are in inches (millimeters).
2. Tolerance of  $\pm .010$  (.25) on all non nominal dimensions unless otherwise specified.

**DESCRIPTION**

The QSE243 is a silicon phototransistor with low light level rejection, encapsulated in a medium angle, thin clear plastic sidelooker package.

**FEATURES**

- NPN Silicon Phototransistor with internal base-emitter resistance
- Package Type: Sidelooker
- Medium Reception Angle, 50°
- Clear Plastic Package
- Matching Emitter: QEE213

**ABSOLUTE MAXIMUM RATINGS** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	$T_{OPR}$	-40 to + 100	°C
Storage Temperature	$T_{STG}$	-40 to + 100	°C
Soldering Temperature (Iron) <sup>(2,3,4)</sup>	$T_{SOL-I}$	240 for 5 sec	°C
Soldering Temperature (Flow) <sup>(2,3)</sup>	$T_{SOL-F}$	260 for 10 sec	°C
Collector-Emitter Voltage	$V_{CE}$	30	V
Emitter-Collector Voltage	$V_{EC}$	5	V
Power Dissipation <sup>(1)</sup>	$P_D$	100	mW

**ELECTRICAL / OPTICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ )

Parameter	Test Conditions	Symbol	Min	Typ	Max	Units
Peak Sensitivity		$\lambda_{PS}$	—	880	—	nm
Reception Angle		$\Theta$	—	±25	—	Deg.
Collector Emitter Dark Current	$V_{CE} = 15 \text{ V}$ , $E_e = 0$	$I_D$	—	—	100	nA
Collector Emitter Breakdown	$I_C = 100 \mu\text{A}$	$BV_{CEO}$	30	—	—	V
Saturation Voltage	$E_e = 1 \text{ mW/cm}^2$ $I_C = 0.1 \text{ mA}^{(5)}$	$V_{CE}(\text{sat})$	—	—	0.4	V
Rise Time	$V_{CC} = 5 \text{ V}$ , $R_L = 1000 \text{ V}$	$t_r$	—	15	—	μs
Fall Time	$I_C = 1 \text{ mA}$	$t_f$	—	15	—	μs
Light Current Slope <sup>(6)</sup>	$V_{CE} = 5 \text{ V}$ , $E_{e1} = 1 \text{ mW/cm}^2{}^{(5)}$ $E_{e2} = 0.5 \text{ mW/cm}^2{}^{(5)}$	$I_{LS}$	1.0			$\text{mA/mW/cm}^2$
Knee Point <sup>(5,7)</sup>	$V_{CE} = 5 \text{ V}$	$E_{ek}$		0.125		$\text{mW/cm}^2$

**NOTES**

1. Derate power dissipation linearly 1.33 mW/°C above 25°C.
2. RMA flux is recommended.
3. Methanol or isopropyl alcohols are recommended as cleaning agents.
4. Soldering iron 1/16" (1.6 mm) minimum from housing.
5.  $\lambda = 950 \text{ nm}$ , GaAs source
6. The slope is defined by  $(I_{C1}-I_{C2}) / (E_{e1}-E_{e2})$  where  $I_{C1}$  is the collector current at  $E_{e1}$  and  $I_{C2}$  the collector current at  $E_{e2}$ .
7. Knee point is defined as being required to increase  $I_C$  to 50 μA.

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